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ieee.icia@gmail.com / +86 137 1350 0061

Call for Papers

Sponsored by the IEEE Robotics and Automation Society, the 16th event of the ICIA conference series will be held from July 18 to July 21, 2019 in Dali, Yunnan, China. Dali is situated in the transition area between the dramatic valleys of the eastern Tibetan Plateau and the distinctive mountains of the western Yungui Plateau. The Dali city surrounds the Erhai Lake between the Cang Mountains to the west and the Mount Jizu to the east. The Dali Old Town is situated on a fertile plain between the Cang Range and Erhai. This plain has traditionally been settled by the Bai and Yi minorities. The natural beauty of the Cang Range and Erhai Lake is breathtakingly astounding. The ICIA 2019 conference promises to offer the participants a great experience with excellent technical and social programs. High quality manuscripts reporting the original research results and innovations in all aspects of information, automation, artificial intelligence, robotics, image processing, computer vision, DSP, BME and related areas as well as their applications are invited.

Contributed Papers: Papers are solicited in all areas mentioned above. All papers must follow the IEEE Xplore® PDF format for IEEE Xplore database and El index. Organized sessions (OS) are welcome.

Best Paper Competitions: All the received papers will be automatically considered and evaluated for the following best paper awards:

- Best Conference Paper Award
- Best Student Paper Award
- Best Paper in Information Award
- Best Paper in Automation Award
- $R\pi$ Labs Best Paper in Al Award
- GaiTech Best Paper in Robotics Award

Important Dates:

May 15, 2019: Submission of full papers in PDF format & OS proposals June 15, 2019: Notification of paper and OS proposal acceptance June 30, 2019: Submission of final accepted papers in IEEE PDF format